ON Semiconductor

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Configurable Multifunction Gate

NL7SZ97

The NL7SZ97 is an advanced high-speed CMOS multifunction gate. The device allows the user to choose logic functions MUX, AND, OR, NAND, NOR, INVERT and BUFFER. The device has Schmitt-trigger inputs, thereby enhancing noise immunity.

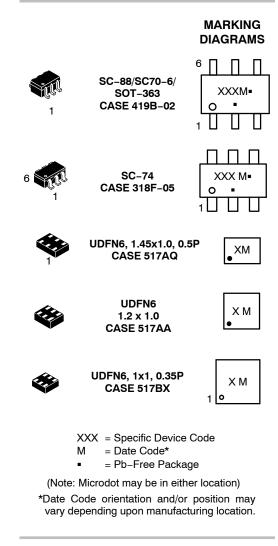
Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 3.3 ns t_{PD} at $V_{CC} = 5 V (Typ)$
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Sink 24 mA at 3.0 V
- Available in SC-88, SC-74 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



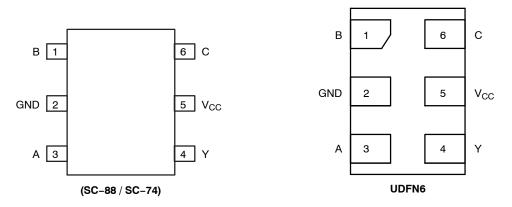
ON Semiconductor®

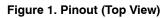
www.onsemi.com

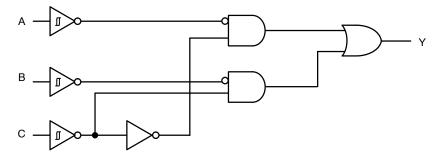


ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.









PIN ASSIGNMENT

Pin	Function
1	В
2	GND
3	А
4	Y
5	V _{CC}
6	С

FUNCTION TABLE*

	Input				
А	В	С	Y		
L	L	L	L		
L	L	Н	L		
L	Н	L	Н		
L	Н	Н	L		
Н	L	L	L		
Н	L	Н	Н		
Н	Н	L	Н		
Н	Н	Н	Н		

*To select a logic function, please refer to "Logic Configurations section".

LOGIC CONFIGURATIONS

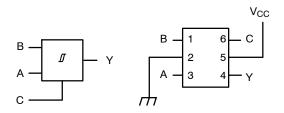


Figure 3. 2–Input MUX

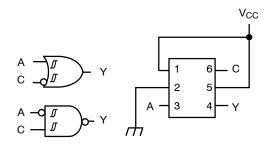


Figure 5. 2–Input OR with Input C Inverted (When B = "H")

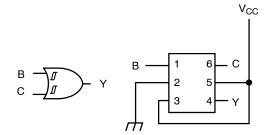


Figure 7. 2–Input OR (When A ="H")

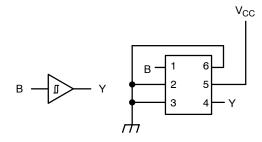


Figure 9. Buffer (When A = C = "L")

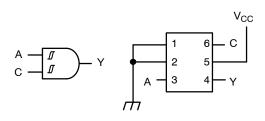


Figure 4. 2-Input AND (When B = "L")

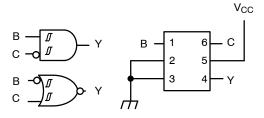


Figure 6. 2–Input AND with Input C Inverted (When A = "L")

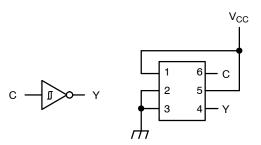


Figure 8. Inverter (When A = "L" and B = "H")

MAXIMUM RATINGS

Symbol	Para	Value	Unit		
V _{CC}	DC Supply Voltage	SC-88 (NLV) SC-88, SC-74, UDFN6	-0.5 to +7.0 -0.5 to +6.5	V	
V _{IN}	DC Input Voltage	SC-88 (NLV) SC-88, SC-74, UDFN6	-0.5 to +7.0 -0.5 to +6.5	V	
V _{OUT}	DC Output Voltage SC-88 (NLV)	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0	V	
	DC Output Voltage SC-88, SC-74, UDFN6	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5	V	
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA	
Ι _{ΟΚ}	DC Output Diode Current	DC Output Diode Current V _{OUT} < GND			
I _{OUT}	DC Output Source/Sink Current	±50	mA		
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Gr	±100	mA		
T _{STG}	Storage Temperature Range		-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for	10 Secs	260	°C	
TJ	Junction Temperature Under Bias		+150	°C	
θ_{JA}	Thermal Resistance (Note 2)	SC-88 SC-74 UDFN6	377 320 154	°C/W	
P _D	Power Dissipation in Still Air	SC-88 SC-74 UDFN6	332 390 812	mW	
MSL	Moisture Sensitivity		Level 1		
F _R	Flammability Rating Oxygen	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
V _{ESD}	ESD Withstand Voltage (Note 3)	Human Body Mode Charged Device Model (NLV) Charged Device Model	>2000 >200 N/A	V	
ILATCHUP	Latchup Performance (Note 4)	(NLV)	±500 ±100	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Applicable to devices with outputs that may be tri-stated.

 Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
 CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	DC Input Voltage	0	5.5	V
V _{OUT}		ode (High or Low State)0Gri-State Mode (Note 1)0Down Mode (V _{CC} = 0 V)0	V _{CC} 5.5 5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
t _r , t _f	Input Rise or Fall Rate	$\begin{array}{c} V_{CC} = 1.65 \ V \ to \ 1.95 \ V \\ V_{CC} = 2.3 \ V \ to \ 2.7 \ V \\ V_{CC} = 3.0 \ V \ to \ 3.6 \ V \\ V_{CC} = 4.5 \ V \ to \ 5.5 \ V \end{array} \begin{array}{c} 0 \\ 0 \\ \end{array}$	No Limit No Limit No Limit No Limit	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

		V _{CC}		Γ _A = 25°(b		s ≤ T _A 5°C		; ≤ T _A 25°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _T +	Positive Input		1.65	-	-	1.4	-	1.4	-	1.4	V
	Threshold Voltage		2.3	-	-	1.8	-	1.8	-	1.8	
			3.0	-	-	2.2	-	2.2	-	2.2	
			4.5	-	-	3.1	-	3.1	-	3.1	
			5.5	-	-	3.6	-	3.6	-	3.6	
V _T -	Negative Input		1.65	0.2	-	-	0.2	-	0.2	-	V
	Threshold Voltage		2.3	0.4	-	-	0.4	-	0.4	-	
			3.0	0.6	-	-	0.6	-	0.6	-	
			4.5	1.0	-	-	1.0	-	1.0	-	
			5.5	1.2	-	-	1.2	-	1.2	-	
V _H	Input Hysteresis		1.65	0.1	0.48	0.9	0.1	0.9	0.1	-	V
	Voltage		2.3	0.25	0.75	1.1	0.25	1.1	0.25	-	
			3	0.4	0.93	1.2	0.4	1.2	0.4	-	
			4.5	0.6	1.2	1.5	0.6	1.5	0.6	-	
			5.5	0.7	1.4	1.7	0.7	1.7	0.7	-	
V _{OH}	High-Level Output Voltage	I _{OH} = -50 μA	1.65 to 5.5	V _{CC} - 0.1	V _{CC}	-	V _{CC} - 0.1	-	V _{CC} - 0.1	-	V
	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -4 mA	1.65	1.20	1.52	-	1.20	-	1.20	-	
		I _{OH} = -8 mA	2.3	1.9	2.1	-	1.9	-	1.9	-	
		I _{OH} = -16 mA	3	2.4	2.7	-	2.4	-	2.4	-	
		I _{OH} = -24 mA	3	2.3	2.5	-	2.3	-	2.3	-	
		I _{OH} = -32 mA	4.5	3.8	4	-	3.8	-	3.8	-	
V _{OL}	Low-Level Output Voltage	I _{OL} = 100 μA	1.65 to 5.5	-	-	0.1	-	0.1	-	0.1	V
	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 4 mA	1.65	-	0.08	0.45	-	0.45	-	0.45	
		I _{OL} = 8 mA	2.3	-	0.2	0.3	-	0.3	-	0.4	
		I _{OL} = 16 mA	3	-	0.28	0.4	-	0.4	-	0.5	
	I _{OL} = 24 mA	3	-	0.38	0.55	-	0.55	-	0.55		
		I _{OL} = 32 mA	4.5	-	0.42	0.55	-	0.55	-	0.65	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	1.65 to 5.5	_	_	+0.1	_	+1.0	-	+1.0	μA
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	_	-	1.0	-	10	-	10	μA
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5	-	-	1.0	-	10	-	10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

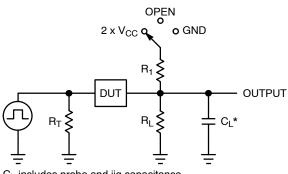
AC ELECTRICAL CHARACTERISTICS

				r	Γ _A = 25°0	•		s ≤ T _A 5°C		≤ T _A 25°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}		$\begin{array}{l} R_{L} = 1 \ k\Omega, \\ C_{L} = 30 \ pF \end{array}$	1.65 to 1.95	-	8.6	14.4	-	14.4	-	14.4	ns
		$ \begin{array}{c} {\sf R}_{\sf L} = 500 \ \Omega, \\ {\sf CL} = 30 \ {\sf pF} \end{array} $	2.3 to 2.7	-	5.1	8.3	-	8.3	-	8.3	
		$R_L = 500 \Omega$,	3.0 to 3.6	-	3.9	6.3	-	6.3	_	6.3	
		C _L = 50 pF	4.5 to 5.5	-	3.3	5.1	-	5.1	-	5.1	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V_{CC} = 3.3 V, V_{IN} = 0 V or V_{CC} 10 MHz, V_{CC} = 5.0 V, V_{IN} = 0 V or V_{CC}	16 19.5	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

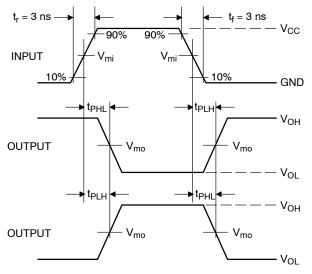


Switch Position	C _L , pF	R_L, Ω	R ₁ , Ω		
Open	See AC Characteristics Table				
$2 \times V_{CC}$	50	500	500		
GND	50	500	500		
	Position Open 2 x V _{CC}	Position See AC Character Open See AC Character 2 x V _{CC} 50	Position Image: Constraint of the set of the se		

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 10. Test Circuit



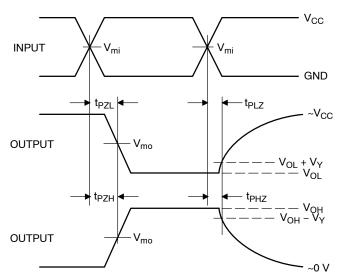


Figure 11. Switching Waveforms

		V _m		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V
1.65 to 1.95	V _{CC} / 2	V _{CC} / 2	V _{CC} / 2	0.15
2.3 to 2.7	V _{CC} / 2	V _{CC} / 2	V _{CC} / 2	0.15
3.0 to 3.6	V _{CC} / 2	V _{CC} / 2	V _{CC} / 2	0.3
4.5 to 5.5	V _{CC} / 2	V _{CC} / 2	V _{CC} / 2	0.3

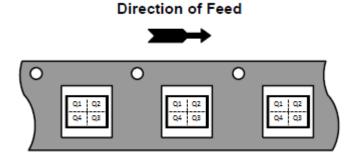
ORDERING INFORMATION

Device	Package			Shipping [†]
NL7SZ97DFT2G	SC-88 (Pb-Free)	МК	Q4	3000 / Tape & Reel
NLV7SZ97DFT2G*	SC-88 (Pb-Free)	МК	Q4	3000 / Tape & Reel
NL7SZ97DBVT1G	SC-74 (Pb-Free)	AN	Q4	3000 / Tape & Reel
NL7SZ97MU1TCG (In Development)	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	5 (Rotated 270° CW)	Q4	3000 / Tape & Reel
NL7SZ97MU2TCG (In Development)	UDFN6, 1.2 x 1.0, 0.4P	D (Rotated 270° CW)	Q4	3000 / Tape & Reel
NL7SZ97MU3TCG (In Development)	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	TBD	Q4	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

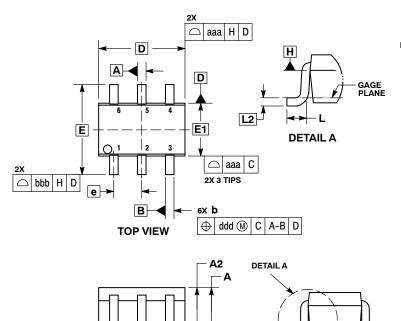
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable.

Pin 1 Orientation in Tape and Reel



PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**



NOTES:

С

END VIEW

- NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
 DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 DIMENSION D ODES NOT INCLUDE DAMBAR PROTRUSION
- LEAD BE IWEEN 0.08 AND 0.15 FROM THE TIP. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION & AT MAXIMUM MATERIAL CONDI-TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. 7.

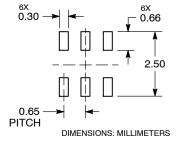
	MIL	LIMETE	ERS		INCHES	~	
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е	(0.65 BS	С	0	.026 BS	С	
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2		0.15 BS	SC	0.006 BSC			
aaa	0.15				0.006		
bbb	0.30			0.012			
CCC	0.10				0.004		
ddd		0.10			0.004		

RECOMMENDED **SOLDERING FOOTPRINT***

SIDE VIEW

A1

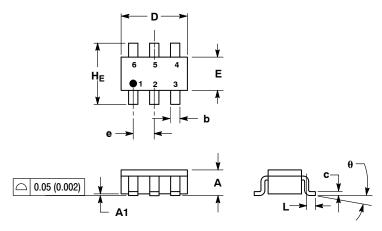
ex □ ccc C



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

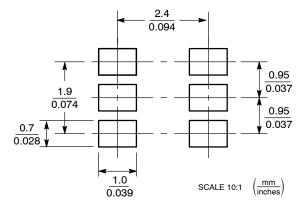
SC-74 CASE 318F-05 **ISSUE N**



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

	MILLIMETERS				INCHES	IES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.37	0.50	0.010	0.015	0.020	
С	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
Е	1.30	1.50	1.70	0.051	0.059	0.067	
е	0.85	0.95	1.05	0.034	0.037	0.041	
L	0.20	0.40	0.60	0.008	0.016	0.024	
HE	2.50	2.75	3.00	0.099	0.108	0.118	
θ	0°	-	10°	0°	-	10°	

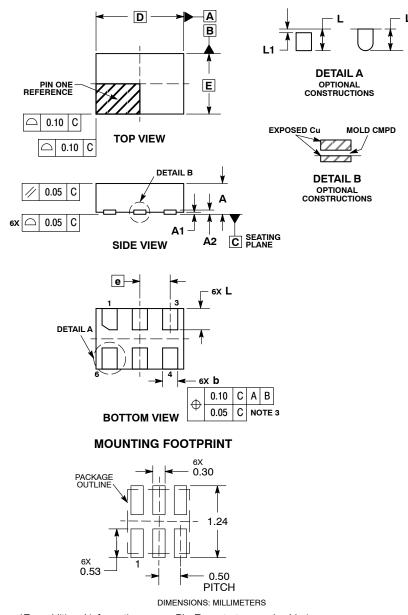
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P CASE 517AQ ISSUE O



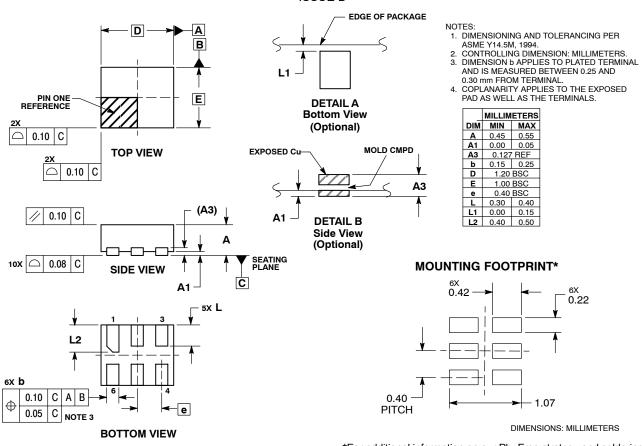
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NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.45	0.55		
A1	0.00	0.05		
A2	0.07 REF			
b	0.20	0.30		
D	1.45 BSC			
Е	1.00 BSC			
е	0.50 BSC			
L	0.30	0.40		
L1		0.15		

PACKAGE DIMENSIONS

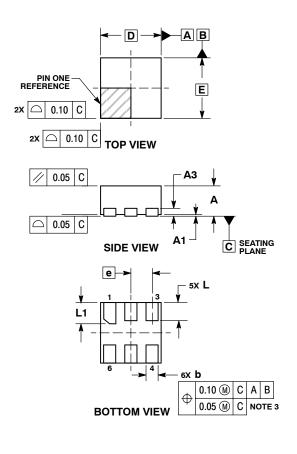
UDFN6, 1.2x1.0, 0.4P CASE 517AA-01 ISSUE D



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

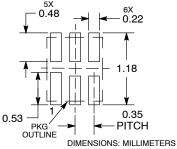
UDFN6, 1x1, 0.35P CASE 517BX ISSUE O



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME V14 5M 1994
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF

BURRS AND MOLD FLASH.						
	MILLIN					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.13 REF					
b	0.12	0.22				
D	1.00 BSC					
Е	1.00 BSC					
е	0.35					
L	0.25	0.35				
L1	0.30	0.40				

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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